PRODUCT DATA SHEET

PicoShot® Conditioner C-1

Purging Gel

Introduction

Indium Corporation's PicoShot® Conditioner C-1 is a chemically benign bright blue-colored viscous gel material designed to allow the rapid purging and cleaning of jetting, dispense, and microdispense systems without the use of liquid solvents. It has been formulated to be non-corrosive and non-reactive with these systems.

Features

- Distinctive blue color aids in visual purge endpoint detection
- · Rheology ensures fast removal of all solder powder particulates and reactive flux from flow path
- Prevents inconsistent dispense volumes and clogging due to solder paste dry-out
- Allows easy equipment cleaning and maintenance to ensure long dispensing valve and tip life
- Compatible with Indium Corporation's no-clean and solvent-clean dispensing and jetting solder paste and TACFlux® products

General Application Notes

Note: Jetting or microdispense equipment manufacturer instructions should be followed, in addition to the general guidelines given below.

If stored cold, all materials should stabilized to ambient temperature before use.

Purge-Out Paste Using Purging Gel

- 1. Remove the syringe of paste from the equipment, unscrewing the luer lock to release.
- 2. Replace with a syringe of **PicoShot® Conditioner C-1**, securing it in place using the luer lock.
- 3. Start the flow of conditioner through the jetting or microdispense equipment, until the characteristic blue gel material starts to appear at the head. Ensure that C-1 Conditioner flows freely from tip and the color of material is similar to that in the syringe.
- 4. Remove the syringe of PicoShot® Conditioner C-1, unscrewing the luer lock to release.
- 5. The equipment may now be shut down.

Purge-Out Gel Using Solder Paste

- 1. Secure a syringe of the desired jetting or microdispense paste (Indium Corporation solder paste is recommended) in place using the luer lock.
- 2. Start the flow of paste through the jetting or dispense equipment to purge the flow path of gel, and watch for solder paste to appear at the head. Ensure a uniform output of solder paste is observed.
- 3. Dispense for another 15-20 seconds to ensure complete purging of all gel from the system.
- Jetting or dispense equipment may now be used, after any other recommended equipment manufacturer startup procedures have been completed.



Packaging

PicoShot® Conditioner C-1 is available in both 30cc EFD Optimum (standard dispense and jetting systems) and Iwashita (Mycronic MY500, 600, 700 system compatible) syringes.

Storage

PicoShot® Conditioner C-1 may be stored at room temperature with a shelf life of 6 months.

Cleaning

C-1 Conditioner can be cleaned with hot water and detergent or saponified water, if necessary.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at http://www.indium.com/sds

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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

From One Engineer To Another

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